

## Bluetooth® SMD Module

### Module Solder Reflow Conditions

1) Leaded Solder Reflow Condition

Reflow Temperature: 493.15K (220 degree), Time 20 to 30 sec,  
Peak 503.15K (230 degree) Max

Preheat Temperature: 433.15K +/- 10K (160 degree +/- 10 degree),  
Time 90 sec +/- 30 sec

2) Lead-free Solder Reflow Condition

Reflow Temperature: 503.15K (230 degree), Time 30 to 40 sec,  
Peak 523.15K (250 degree) Max

Preheat Temperature: 438.15K +/- 15K (165 degree +/- 15 degree),  
Time 90 to 120 sec

Reflow Time: One time

### ESD Susceptibility

This module meets the below ESD test specifications.

1) Human Body Model (HBM)

+/-2.0k Volts as C=100pF and R=1.5kohms  
Number of test: Three times  
Measurement shall be conducted after that.

2) Machine Model (MM)

+/-200 Volts as C=200pF / R=0 ohm  
Number of test: One time  
Measurement shall be conducted after that.